

CSM Series

Board Mount Heat Sink For TO-220 Devices



The economically priced CSM Series is suitable for use with TO-220 devices found in active components as well as power resistors. With surface areas ranging from 1188 Sq. mm to 6645 Sq. mm, the CSM family comes in 5 configurations, all of them with Black Anodized surface treatment. These heatsinks

offer a range of thermal performance from 18.0 to 9.8 C/W. Each device offers solder able mounting feet and anywhere from 1, 2 or 3 mounting holes are available for convenient device attachment.

SERIES SPECIFICATIONS

Heatsink Part Number	Surface Area (in ² / mm ²)	Weight (oz / g)	Length L (mm)	Thermal Res.* (°C/W)
CSM221-12AE	1.84 / 1,188	0.13 / 3.7	12	18.0
CSM221-28AE	4.30 / 2,772	0.3 / 8.5	28	12.8
CSM221-40AE	6.14 / 3,960	0.43 / 12.2	40	12.1
CSM222-30AE	6.25 / 4,029	0.5 / 14.2	30	11.3
CSM223-50AE†	10.30 / 6,645	0.6 / 17.0	50	9.8

*Free convection at 10 watts dissipation

†Available for custom orders only, not offered as standard length

CHARACTERISTICS

Heat Dissipation

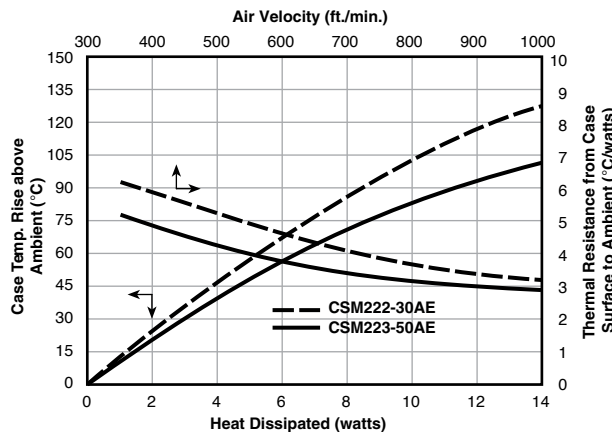
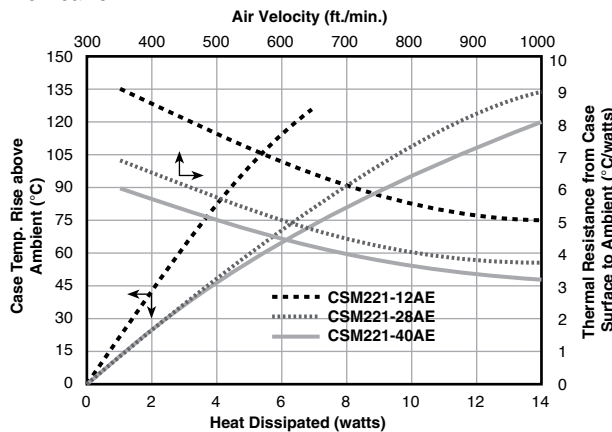
Heat dissipation is the total for ALL DEVICES attached to the heat sink

Heat Sink Aluminum Alloy 6063-T5 or Equivalent with either degreased or black anodized finish.

Solder Foot Cold-rolled Steel, surface tin plated.

Interface Thermal Resistance for improvement, use thermal joint compound, 0.005 Grafoil (TGon 800 by Laird), or phase change material (Hi-Flow by Bergquist)

Insulator (Optional) Sil-Pad 900-S, K6 800-S and K10 by Bergquist



(continued)

